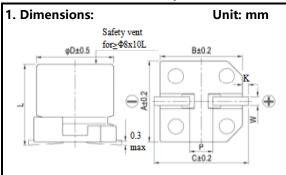


Specification: CAE157M1VHUZFJ2TR1A

CDUZ Series



φD	L	A	В	С	P	K	W
4	5.4 -0.3/+0.5	4.3	4.3	5.0	1.0±0.2	0.5max	0.5~0.8
5	5.4 -0.3/+0.5	5.3	5.3	6.0	1.5±0.2	0.5max	0.5~0.8
6.3	5.4 -0.3/+0.5	6.6	6.6	7.2	2.1±0.2	0.5max	0.5~0.8
6.3	7.7 -0.3/+0.5	6.6	6.6	7.2	2.1±0.2	0.5max	0.5~0.8
8	6.5 -0.3/+0.5	8.3	8.3	9.1	3.1±0.2	0.5max	0.8~1.1
8	10.2±0.5	8.3	8.3	9.1	3.1±0.2	0.5max	0.8~1.2
10	7.7±0.5	10.3	10.3	11.0	4.5±0.2	0.5max	0.8~1.3
10	10.2±0.5	10.3	10.3	11.0	4.5±0.2	0.5max	0.8~1.3

2.Technical Parameter:

Aillen	Cap.	Cap.	Rate	Surge	Oper.	Case Size	Leakage	Disspation	ESR Max	ESR Max	R.C Max	R.C Max	Load
	(µF)	Tol.(%)	3.7.14	37.14	T	D#I	Current1)	Factor Max	at +20°C	at +20°C	at 105°C	at 85°C	Life at
P/N	at	at	Volt . (VDC)	(VDC)	Volt . Temp. (VDC) (°C)	D*L (mm)	Max at	at +20°C	120Hz	100kHz	100kHz	120Hz	105°C
	+20°C	+20°C	(VDC)	(VDC)	(C)		+20°C(μA)	120Hz(%)	(Ω)	(Ω)	(mA rms)	(mA rms)	(hours)
CAE157M1VHUZFJ2TR1A	150	±20%	35	40.3	-55~105	8x10.2	52.5	12	/	0.16	600	/	3000

Remark::

1). L.C.≤0.01CVor 3 (μA) whichever is greater, After 2 minute measured with rated working voltage applied, C: Capacitance (μF) V: Rated DC Working Voltage (V).

3. Multiplier For Ripple Current

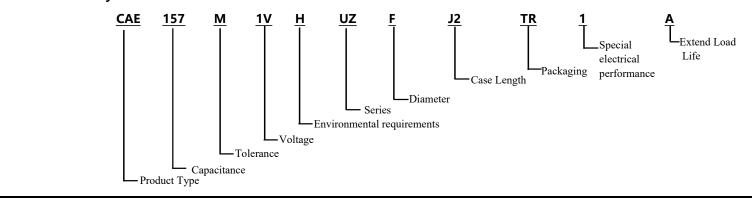
Remark: When capacitors are operated at temperatures other than +105°C, and frequency other than 100kHz, the maximum Ripple Current(R.C.) must be multiplied by the factors shown in below table.

Frequency	50Hz	120Hz	300Hz	1kHz	≥10kHz
Coefficient	0.64	0.70	0.75	0.83	1.00

4. Characteristics

ltem	Characteristics										
	The capacitor is stored at a temperature of 105°C ±2 with rated voltage applied continuously for 3000+48/0 hours, Then the product should be tested after 16 hours recovering time at atmospheric conditions. The result should meet the following table:										
Load Life	Capacitance Change	citance Change Within ±30% of initial value									
Load Life	Dissipation Factor		Not mor	e than 300	% of the spe	cified value					
	Leakage Current	Leakage Current Not more than the specified value									
Shelf Life	Following this period the cal 4~8 hours.Next they shall be	pacitors e connec	no voltage applied at a temperature of $105\pm2^{\circ}$ C for $1000+48/0$ hours. shall be removed from the test chamber and be allowed to stabilized at room temperature for cted to a series limiting resistor($1k\pm100\Omega$) with D.C. rated voltage applied for 30 min. After which and then, tested the characteristics.								
Shell Life	Capacitance Change	Within ±30% of initial value									
	Dissipation Factor	Not more than 300% of the specified value									
	Leakage Current	Not more than 200% of the specified value									
	Rated Voltage (V)	6.3	10	16	25	35	50	63	80		
Low Temperature	Z-25°C/Z+20°C (120Hz)	4	3	2	2	2	2	2	2		
Stability	Z-55°C/Z+20°C (120Hz)	8	5	4	3	3	3	3	3		

5. Part Number System:



Specification: CAE157M1VHUZFJ2TR1A

6. Welding methods and applicability

6.1 Methods the following:

Reflow soldering: please follow the temperature condition during welding. If high temperature is used, please measure and inform the capacitor temperature and reflow soldering condition. The product size is larger and its rising temperature is slower. It is not necessary to adjust the temperature of the reflow solder in accordance with the size of the product. For example, the products of 4 and 10 will be installed in the PCB over tin furnace.

6.2 Precautions for soldering tin:

Related factors of reflow soldering temperature:

The product size is larger and its temperature rises slowly

Product installation position: The temperature of PCB center is lower than that of PCB.

6.3 Reflow soldering:

If possible, avoid reflow soldering twice

If repeated reflux is unavoidable, measure and inform the first and second reflux temperature, and the time of reflow soldering

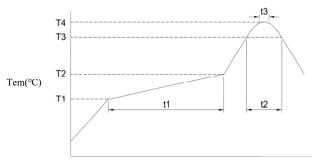
6.4 Please do not 3 times of reflow soldering:

Please follow the following conditions when soldering tin soldering:

6.4.1 Soldering iron maximum temperature: 350±5°C

6.4.2 Welding time: 3+1/-0S

Conditions for the use of lead-free reflow soldering.:



Time(S)

Test method and peak temperature permissible range

Products	category	SMD aluminum electrolytic capacitor							
Rated vol	tage (V)	4~	·50	≥63	4~100		≥160		
Produ	ct size	4~6	6.3x5.4~	-7.7	8~	18	≥12.5		
preheating	Tem $(T_1 \sim T_2, \ ^{\circ}C)$	150~180							
	Time (t_1) Max,S	100							
The duration of the	Tem $(T_3, ^{\circ}C)$	217	230	217	217	230	217		
	Time (t_2) Max,S	90	60	60	60	40	40		
The highest	Tem (T₄, °C)	20	60	250	250		240		
temperature	Time (t_3) Max,S	5							
Return tl	ne number	1							

Remark:

- 1)Please contact us if the conditions of use are higher than those listed above;
- 2)When performing second reflow soldering, please make sure the temperature of capacitor has cooled to 5 ~ 35 °C;
- 3)If the reflow condition is based on IPC/JEDEC(J-STD-020), please contact us;



4)Reflow Soldering Considerations

Reflow soldering will reduce the rated electrostatic capacity of the product, and it should be confirmed whether reflow soldering condition meets the specification of recommended reflow soldering

Although the actual reflow condition change is still based on the reflow soldering method, please note that the highest temperature and the electrode terminal at the bottom of the aluminum shell must not exceed the maximum temperature

OP - CAP products during the process of reflow heating temperature should increase to more than 200 °C

If the reflow condition temperature or duration is greater than the above table, the OP-CAP product will be damaged. The electrostatic capacity of the product is reduced by about 50%, the leakage current is large (up to m A), and the outside of the capacitor is damaged

7.Recommended Land Size (Unit: mm)

Size	X	Y	a	Pictorial Representation
Ф4	1.6	2.6	1	
Ф5	1.6	3	1.4	Y
Ф6.3	1.6	3.5	1.9	a a
Φ8	2.5	3.5	3	Y
Ф10	2.5	4	4	< ×

8. Taping Specifications:

Applicable standard JIS C0806 and IEC 60286.

8.1Carrier Tape and Dimension

Size : $\emptyset 4 \sim \emptyset 10$

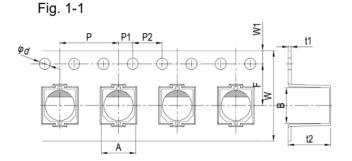
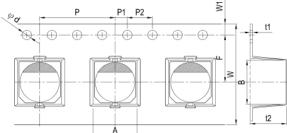


Fig. 1-2



Size	W (mm)	P (mm)	F (mm)	A (mm)	B (mm)	t ₂ (mm)	Φd	P_1	P_2	\mathbf{t}_1	\mathbf{W}_1	Applicable
Φ4*5.4	12	8	5.5	4.7	4.7	5.8	1.5	2.0	4.0	0.4	1.75	Fig.1-1
Φ5*5.4	12	12	5.5	6.0	6.0	5.8	1.5	2.0	4.0	0.4	1.75	
Φ6.3*5.4	16	12	7.5	7.0	7.0	5.8	1.5	2.0	4.0	0.4	1.75	
Φ6.3*7.7	16	12	7.5	7.0	7.0	8.3	1.5	2.0	4.0	0.4	1.75	
Φ8*6.5	16	12	7.5	8.7	8.7	6.8	1.5	2.0	4.0	0.4	1.75	Fig.1-2
Φ8*10.2/10.5	24	16	11.5	8.7	8.7	11	1.5	2.0	4.0	0.4	1.75	
Ф10*7.7	24	16	11.5	10.7	10.7	8.7	1.5	2.0	4.0	0.4	1.75	
Ф10*10.2/10.5	24	16	11.5	10.7	10.7	11	1.5	2.0	4.0	0.4	1.75	